

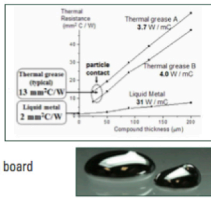
# LIQUID METAL INNOVATIONS FOR HIGH-PERFORMANCE THERMAL INTERFACE MATERIALS (TIMs)



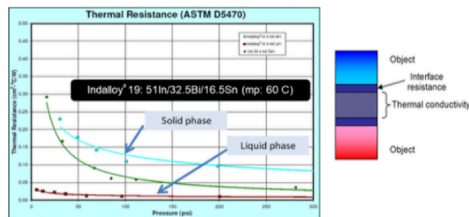
Tim Jensen, Senior Product Manager, Engineered Solder Materials, Indium Corporation

## Liquid Metals as a TIM<sup>®</sup>

- Pros
  - Relatively high thermal conductivity
  - Excellent wetting to surfaces
  - No soldering or surface metallization needed
  - Thin bondline possible
- Cons
  - Must be contained to minimize spread elsewhere on board
  - More difficult to handle and apply



## Thermal Resistance: Solid vs. Liquid



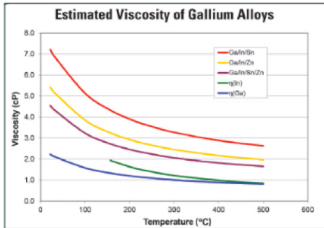
## Basic Liquid Metal Properties

Metal/Alloy	Melting Point (°C)	Composition	Density (g/cm <sup>3</sup> )	Thermal Conductivity (W/mK)
Gallium	11	66.5Ga/20.5In/13.0Sn	6.32	25
EGaIn	16	75.5Ga/24.5In	6.35	26
EGaSn	21	81.6Ga/8.4Sn	6.01	28

Base Elemental Properties				
Indium	157	1000In	7.31	87
Tin	235	1000Sn	7.28	73
Gallium	30	1000Ga	5.90	31

- Mixing of metals generally lowers both the melting point and thermal conductivity
- Liquid metals are high-density and low viscosity



## Liquid Metal Supercooling

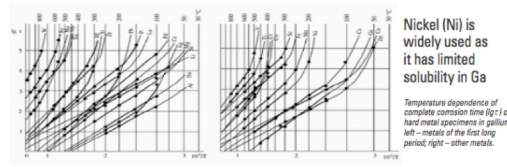


## Liquid Metal Challenge #1:<sup>21</sup> Avoid Aluminum

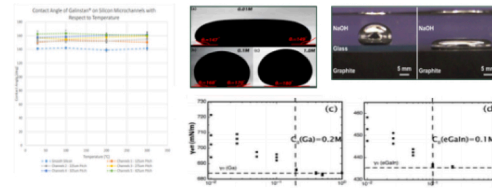
The reaction process of gallium and aluminum is not actually a corrosion process per se. The Ga dissolves the grain boundaries, causing the Al structure to crumble.



## Alternative Metals to Aluminum<sup>22</sup>

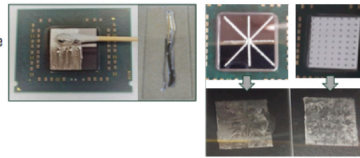


## Liquid Metal Challenge #2:<sup>16</sup> Ga Surface Tension



## Surface Tension vs. Wetting

- Ga will wet to most any surface but requires some agitation
- Application method and pattern will need optimization to ensure complete coverage



## Liquid Metal Challenge #3: Automation

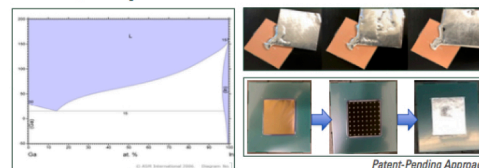
- Standard dispensing is a challenge due to high-density, low viscosity
- Jetting more easily implemented
- Alloy purity and compositional accuracy is critical



## Solid/Liquid Hybrid (SLH) Metal TIM Innovation

- Technology Basics
  - Combine metal that is liquid at room temperature with one that is solid at room temperature
  - Liquid material provides wetting and low interfacial resistance
  - Solid material creates structure, minimizing the risk of pump-out
  - Solid material must have limited solubility in the liquid alloy
- Methods of Application
  - Premix solid and liquid to create a slurry
  - Combine solid and liquid material at the time of use

## SLH: Ga/In Liquid with In Preform

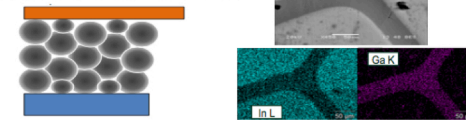


## Gallium Grain Boundary Flow

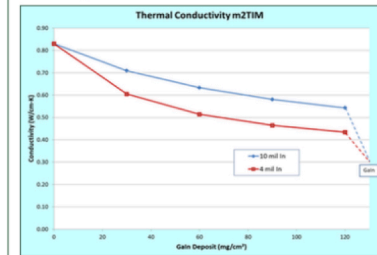


## The Result: A Metallic Sponge

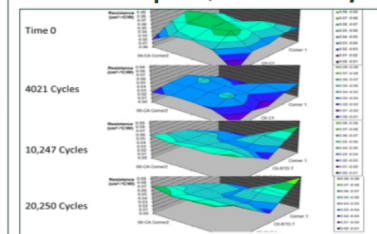
Liquid alloy is contained but provides shear relief



## SLH Improves Thermals



## SLH Won't Pump-Out (0-80W Power Cycling)



## Summary

- With increasing thermal demands on devices today, liquid metals are re-emerging as viable thermal materials for TIM1, TIM1.5, and TIM2 applications
- There are viable options that address many of the processing challenges of using a liquid metal
- Solid/Liquid Hybrid solutions could emerge as a significant improvement in both thermal performance and lifespan

## Sources

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